

IN THE CLAIMS

Please amend the claims as follows:

1-13. (Canceled)

14. (Previously Presented) A method for manufacturing an information storage medium comprising:

providing a medium having an approximately plane front face and an approximately plane opposite back face, wherein the medium is configured to be read and/or written by a read and/or write device placed facing the front face;

predetermining a distance separating the front face from a magnetic deposit being such that the read and/or write device can read and write the information in the magnetic deposit;

providing recessed areas in the back face having the predetermined distance between the front face and the bottom of the recessed areas; and

providing the magnetic deposit used for information storage within the recessed areas, thereby forming a discrete information storage array on the back face wherein each recessed area is configured to contain at least one magnetic domain representing an elementary bit defined by a magnetization direction.

15. (Previously Presented) The method according to claim 14, further comprising: providing on the back face areas configured to make the medium stiff.

16. (Previously Presented) The method according to claim 14, further comprising:

forming the magnetic deposit in the bottom of the recessed areas using a beam of atoms of at least one magnetic material directed onto the back face of the medium, the beam substantially perpendicular to the back face.

17. (Previously Presented) The method according to claim 14, further comprising:
forming the magnetic deposit on all or part of the sidewalls of the recessed areas using a beam of atoms of at least one magnetic material directed onto the back face of the medium, the beam oblique to the back face.

18. (Previously Presented) The method according to claim 14, further comprising:
providing the front face on a first layer of the medium;
providing the back face on a substrate layer attached to the first layer; and
forming the recessed areas directly in the substrate layer.

19. (Currently Amended) The method according to claim 18, further comprising:
forming the recessed areas through the ~~second~~ substrate layer such that the first layer forms the bottom of the recessed areas.

20. (Previously Presented) The method according to claim 14, further comprising:
forming an etching mask on the back face;
forming the recessed areas by etching through the etching mask;
providing the magnetic deposit to the back face including the etching mask; and
removing the etching mask and the magnetic deposit formed on the etching mask.

21. (Previously Presented) The method according to claim 14, further comprising:

affixing an auxiliary substrate to the back face of the medium.

22. (Currently Amended) The method according to claim 14, further comprising:

forming ~~[[the]]~~ a first layer of the medium on a first substrate;

forming ~~[[the]]~~ a second layer of the medium on the first layer;

forming ~~[[the]]~~ a third layer of the medium on the second layer;

forming the recessed areas through the third layer such that the second layer forms the bottom of the recessed areas;

forming the magnetic deposit in the recessed areas of the third layer on the second layer; and

affixing a second substrate to the third layer.